

# Micro-to-nanoscale characterisation of SRF cavity coatings for the FCC using advanced FIB microscopy

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#### SRF Development





#### **Microstructural characterisation**

Arising need for:

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- Sub-surface characterisation
  - Thin film cross sections
  - Substrate near-surface characterisation
- Elemental mapping
  - Elemental diffusion, segregation, phase identification
- Microscale mechanics
  - Thin film residual stresses T<sub>c</sub> & peel off
- Nanoscale resolution imaging
  - Grain morphology, dislocation density, etc..



## Focused ion beam (FIB) analysis

- Anticipated arising need
- 2<sup>nd</sup> May 2016
- Zeiss XB540 FIB-SEM
  - Sub nanometre resolution
  - Ga<sup>+</sup> with Pt and C deposition
  - Energy Dispersive Spectroscopy (EDS)
  - Atlas 5
  - Scanning Transmission Electron Microscopy
     (STEM) detector





# What is FIB analysis?

- Combined with Scanning Electron Microscope
- Accelerate and focus a beam of ions





#### **FIB** deposition

- Interaction between precursor and ion beam
- Atomic species of interest deposited





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## FIB cross sectional milling

- Pt deposition barrier protect surface
- FIB milling to produce cross section
- Tilt corrected SEM imaging









#### **Example Studies**

Katsiaryna Ilyina-Brunner 10:48 Berlage zaal (1.9) Guillaume Rosaz 11:06 Berlage zaal (1.9)

- High-Power Impulse Magnetron Sputtering
  - Pressure, frequency, voltage bias, coating position
- 18 samples studied

Increased frequency = higher coating rate





#### Surface contamination

- Cu rich deposits observed
- What is the influence on the microstructure?







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## High resolution elemental mapping

- Need to examine elemental diffusion
- Limiting factor on EDS resolution is interaction volume not beam spot size
- Resolution insufficient for thin film samples





## **Transmission EDS**

- Improve resolution reduce interaction volume
- Lamella 100-200 nm thick
- Nanoscale mapping possible
- Problem:
  - 10-20 hours milling time
  - Complex experimental process prone to failure
  - Many samples need investigating





## Solution: 'Rapid' TEDS

- New approach based on 'in-situ' lamella
- No need for risky removal of lamella
- Significant reduction in milling time (4 hours)
- Similar nanoscale resolution EDS mapping possible.









#### **Contamination assessment**

- Electron contrast in cross sectional analysis
- The origins of this:
  - Phase segregation
  - Contamination
  - Electron channelling from grain orientation
- TEDS can provide answers







#### Microscale residual stress analysis

- Residual stress in thin films
  - Peel off & T<sub>c</sub>
- X-ray diffraction conventional approach
  - Average over large area
- Need to quantify at specific locations
  - origins of failure







## Ring-core residual stress analysis

- FIB based technique
- Incremental annular milling
- Relaxation of core
- Record SEM images
- Quantification using digital image correlation
- Compare to finite element simulations
- Quantify residual stress originally present within core





## Nb<sub>3</sub>Sn thin films

• Influence of coating pressure, temp and thermal processing



- Thermal treatment = 650°C for 5 hours
- High compressive stress = higher critical temperature



#### **Residual stress results**

- Highly compressive stresses\*
- Lower temp + higher pressure reduced stress
- Thermal treatment increase in stress





## Cavity substrate analysis

SEM

TEN

DETECTOR

Investigations into Cu cavity

manufacturing techniques ongoing

- Spinning and electro-hydraulic forming
- Scanning transmission electron microscopy
  - TEM lamella







## Potential insights

- Nanoscale behaviour
- Dislocation density
- Surface response
- Grain characteristics
- Comparison between inner & outer surfaces



Further discussion – upcoming presentation Carolina Abajo Clemente 14:30 Berlage zaal (1.9)



## Summary

- Powerful tool with broad spectrum of techniques now possible
- Conventional & tailored techniques directed towards ongoing FCC projects
- Useful results which have improved understanding and facilitated design improvements

If you have any studies which may benefit from FIB analysis, please just get in touch!



### Any questions?



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